

REMARKS

This responds to the Office Action dated January 14, 2008. Claim 1 is amended. Claims 1-26 are pending in this application.

Information Disclosure Statement

Applicant submitted an Information Disclosure Statement and a 1449 Form on December 13, 2004 and a Supplemental Information Disclosure Statement and a 1449 Form on April 21, 2006 and October 29, 2007. Applicant respectfully requests that initialed copies of the 1449 Forms be returned to Applicant's Representatives to indicate that the cited references have been considered by the Examiner.

§102 Rejection of the Claims

Claims 1-6, 8-12, 15-18 and 23-26 were rejected under 35 U.S.C. § 102(b) for anticipation by Hittman et al. (U.S. Patent No. 5,896,267, "Hittman"). Applicant respectfully traverses and has amended claim 1 to clarify the present subject matter. Support for the amendment is found generally within the specification (see e.g., FIGS. 5A, 5B, and 5C).

Applicant respectfully submits that the claims are allowable over Hittman because the cited portions of Hittman fail to teach some of the elements recited or incorporated into the claims. For example, Applicant is unable to find in the cited portions of Hittman, among other things,

a printed circuit interconnect substrate residing on the hermetic side of the hermetic seal, wherein the printed circuit interconnect substrate includes a multi-layer circuit board comprising a buried signal layer between first and second conductive layers, wherein each conductive layer is electrically connected to a constant voltage to form a constant voltage plane,

as presently recited in claim 1 and incorporated into claims 2-6, 8-12, 15-18 and 23-26.

In contrast to the present subject matter, Hittman refers to a metallization pattern 133 formed on an upper surface 138 or opposing surface 124 of substrate 132,¹ and refers to an upper

¹ Hittman, col. 5 lines 29-35.

surface 138' with a first metallization pattern 314 formed thereon.² Therefore, Hittman fails to teach some of the elements recited in claim 1. Dependent claims 2-6, 8-12, 15-18 and 23-26 are believed to be patentable for at least the reasons set forth above.

Additionally, in regard to claim 6, Applicant cannot find in Hittman where the “printed circuit interconnect substrate includes flexible circuit tape” as recited in claim 6. Further, Hittman states that the substrate 132 is formed ... with a plurality of angularly spaced metallized edge recesses formed therein,³ and that the recesses 140 are each formed in a respective perimeter edge 134 and have an arcuate wall that is metallized.⁴ Applicant respectfully submits that a substrate of flexible circuit tape in Hittman would frustrate forming of the arcuate walls, and that the reference to the walls in the substrate actually teaches away from the subject matter in claim 6.

Applicant respectfully requests reconsideration and allowance of claims 1-6, 8-12, 15-18 and 23-26.

§103 Rejection of the Claims

1. Claims 19-22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Hittman in view of Brendel et al. (U.S. Patent No. 6,529,103, “Brendel”). Applicant respectfully traverses the rejection because the cited portions of Hittman and Brendel, either separately or in combination, or when combined with the reasoning of the Office Action, do not disclose, teach, or suggest some of the elements recited or incorporated into the claims. For example, Applicant cannot find

a printed circuit interconnect substrate residing on the hermetic side of the hermetic seal, wherein the printed circuit interconnect substrate includes a multi-layer circuit board comprising a buried signal layer between first and second conductive layers, wherein each conductive layer is electrically connected to a constant voltage to form a constant voltage plane,

which is incorporated into the claims from claim 1. Consequently, Applicant respectfully requests reconsideration and allowance of claims 19-22.

² Hittman, col. 8 lines 4-6 and FIG. 10.

³ Hittman, col. 5 lines 46-49.

⁴ Id., at col. 5 lines 54-56.

2. Claims 13-14 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Hittman in view of Andresakis et al. (U.S. Patent No. 6,657,849, “Andresakis”). Applicant respectfully traverses the rejection because the cited portions of Hittman and Andresakis, either separately or in combination, or when combined with the reasoning of the Office Action, do not disclose, teach, or suggest some of the elements recited or incorporated into the claims. For example, Applicant cannot find

a printed circuit interconnect substrate residing on the hermetic side of the hermetic seal, wherein the printed circuit interconnect substrate includes a multi-layer circuit board comprising a buried signal layer between first and second conductive layers, wherein each conductive layer is electrically connected to a constant voltage to form a constant voltage plane,

which is incorporated into the claims from claim 1. Consequently, Applicant respectfully requests reconsideration and allowance of claims 13-14.

3. Claim 7 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Hittman in view of Chee (U.S. Patent No. 6,657,133). Applicant respectfully traverses the rejection because the cited portions of Hittman and Chee, either separately or in combination, or when combined with the reasoning of the Office Action, do not disclose, teach, or suggest some of the elements recited or incorporated into the claims. For example, Applicant cannot find

a printed circuit interconnect substrate residing on the hermetic side of the hermetic seal, wherein the printed circuit interconnect substrate includes a multi-layer circuit board comprising a buried signal layer between first and second conductive layers, wherein each conductive layer is electrically connected to a constant voltage to form a constant voltage plane,

which is incorporated into claim 7 from claim 1.

Additionally, Applicant respectfully submits that Hittman teaches away from subject matter incorporated into claim 7 from claim 6 at least for the reasons set forth above. Applicant respectfully requests reconsideration and allowance of claim 7.

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 371-2172 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

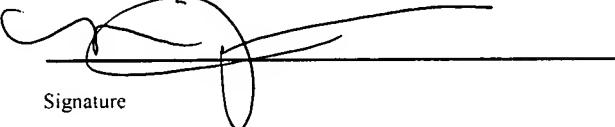
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Date May 14, 2008

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 14 day of May, 2008.

Nicole Jack
Name


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